

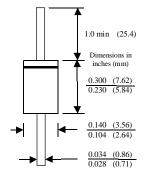
# Discrete POWER & Signal Technologies

## EGP20A - EGP20K

### **Features**

- Glass passivated cavity-free junction.
- High surge current capability.
- Low leakage current.
- Superfast recovery time for high efficiency.
- Low forward voltage, high current capability.





# 2.0 Ampere Glass Passivated High Efficiency Rectifiers

### **Absolute Maximum Ratings\***

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
I <sub>o</sub>	Average Rectified Current .375 " lead length @ T <sub>A</sub> = 55°C	2.0	А
İf(surge)	Peak Forward Surge Current 8.3 ms single half-sine-wave Superimposed on rated load (JEDEC method)	75	А
P <sub>D</sub>	Total Device Dissipation Derate above 25°C	3.13 25	W mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	°C/W
R <sub>θJL</sub>	Thermal Resistance, Junction to Lead	15	°C/W
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TJ	Operating Junction Temperature	-65 to +150	°C

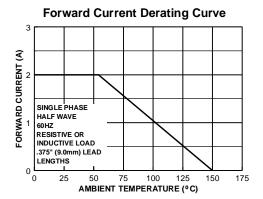
<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

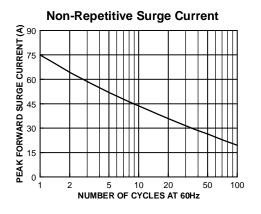
### **Electrical Characteristics**

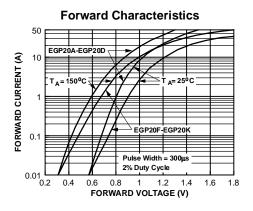
 $T_A = 25$  °C unless otherwise noted

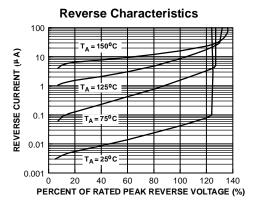
Parameter	Device							Units	
	20A	20B	20C	20D	20F	20G	20J	20K	
Peak Repetitive Reverse Voltage	50	100	150	200	300	400	600	800	V
Maximum RMS Voltage	35	70	105	140	210	280	420	560	V
DC Reverse Voltage (Rated V <sub>R</sub> )	50	100	150	200	300	400	600	800	V
Maximum Reverse Current @ rated $V_R$ $T_A = 25$ °C $T_A = 125$ °C	5.0 100							μ <b>Α</b> μ <b>Α</b>	
Maximum Reverse Recovery Time I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 0.25 A	50 75							nS	
Maximum Forward Voltage @ 2.0 A	0.95 1.25 1.7						.7	V	
Typical Junction Capacitance $V_R = 4.0 \text{ V}, f = 1.0 \text{ MHz}$	70 45						pF		

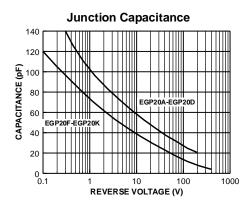
### **Typical Characteristics**

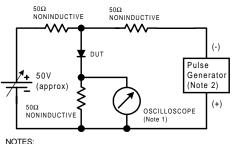


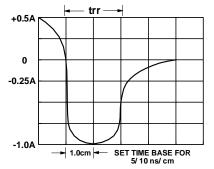












1. Rise time = 7.0 ns max; Input impedance = 1.0 megaohm 22 pf. 2. Rise time = 10 ns max; Source impedance = 50 ohms.

e time = 10 hs max, Source impedance = 50 onins.

Reverse Recovery Time Characterstic and Test Circuit Diagram

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E<sup>2</sup>CMOS<sup>™</sup> PowerTrench<sup>™</sup>

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